

## Power line chokes

Current-compensated ring core triple chokes  
1.7 mH / 2 mH, 500/300 V AC, 10 A, +70 °C

**Series/Type:**            **B82746S4103A02\***

**Date:**                    August 2015

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## Power line chokes

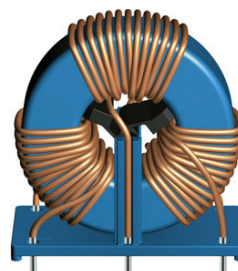
B82746S4103A02\*

### Current-compensated ring core triple chokes

**Rated voltage**      520 / 300 V AC (B82746S4103A020)  
                              500 / 300 V AC (B82746S4103A021)  
**Rated inductance** 1.7 / 2 mH  
**Rated current**      10 A / +70 °C

#### Construction

- Current-compensated ring core triple choke
- Ferrite core with epoxy coating (UL 94 V-0)
- Plastic base plate (UL 94 V-0)
- Plastic spacer (UL 94 V-0)
- Sector winding
- Clearance distance:     $\geq 5.3$  mm (B82746S4103A020)  
                                   $\geq 3.0$  mm (B82746S4103A021)



#### Features

- High resonance frequency
- Approx. 1% stray inductance  
for differential-mode interference suppression
- Suitable for wave soldering
- Design complies with EN 60938-2 (VDE 0565-2)
- RoHS-compatible

#### Applications

- Suppression of common-mode interferences
- Switch-mode power applications
- Frequency converters

#### Terminals

- Ends of winding wires
- Hot-dip tinned

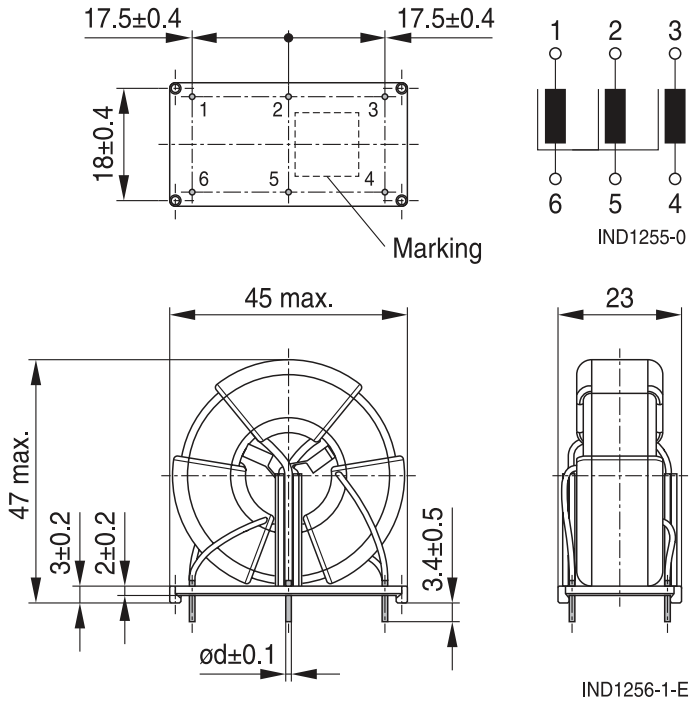
#### Marking

Product brand, ordering code,  
 rated inductance, rated current, rated voltages,  
 date of manufacture (YYWWD.internal ID code), production place identification code

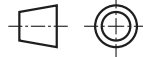
#### Delivery mode

- Cardboard box (B82746S4103A020)
- Blister tray in cardboard box (B82746S4103A021)

# Dimensional drawing and pin configuration



Part tolerances to ISO 2768-cL / ISO 8015.  
Size ISO 14405 (E)  
All dimensions in mm



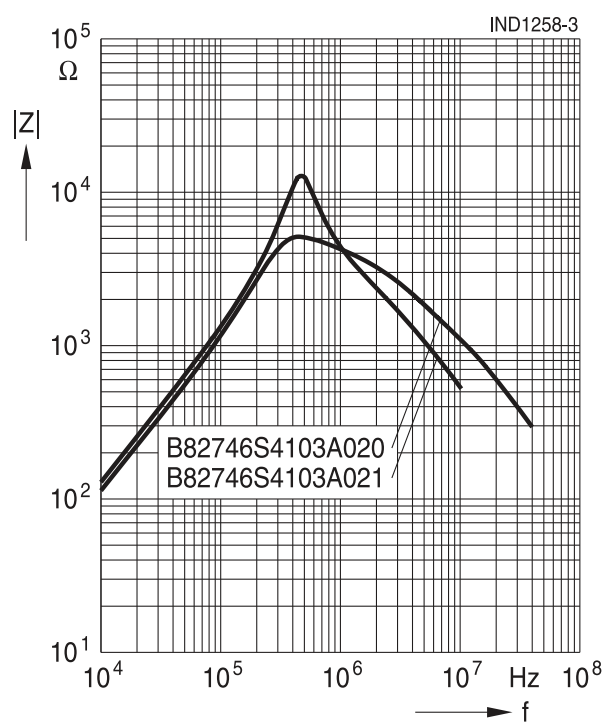
**Power line chokes**
**B82746S4103A02\***
**Current-compensated ring core triple chokes**
**Technical data and measuring conditions**

Rated voltage $V_R$	B82746A4103A020: 520/300 V AC (50/60 Hz) B82746S4103A021: 500/300 V AC (50/60 Hz)
Test voltage $V_{test}$	2800 V AC, 2 s (line/line)
Rated temperature $T_R$	+70 °C
Rated current $I_R$	Referred to 50 Hz and rated temperature
Rated inductance $L_R$	Measured with Agilent 4284A at 10 kHz, 0.1 mA, +20 °C. Inductance is specified per winding.
Inductance tolerance	−30/+50% at +20 °C
Inductance decrease $\Delta L/L_0$	< 10% at DC magnetic bias with $I_R$ , +20 °C
Stray inductance $L_{stray,typ}$	Measured with Agilent 4284A at 10 kHz, 5 mA, +20 °C, typical value
DC resistance $R_{typ}$	Measured at +20 °C, maximum value, specified per winding
Solderability (lead-free)	Sn96.5Ag3.0Cu0.5: +(245 ±5) °C, (3 ±0.3) s Wetting of soldering area ≥ 95% (to IEC 60068-2-20, test Ta)
Resistance to soldering heat (wave soldering)	+(260 ±5) °C, (10 ±1) s (to IEC 60068-2-20, test Tb)
Climatic category	40/125/56 (to IEC 60068-1)
Storage conditions (packaged)	−25 °C ... +40 °C, ≤ 75% RH
Weight	Approx. 80 g (*A020), 90 g (*A021)

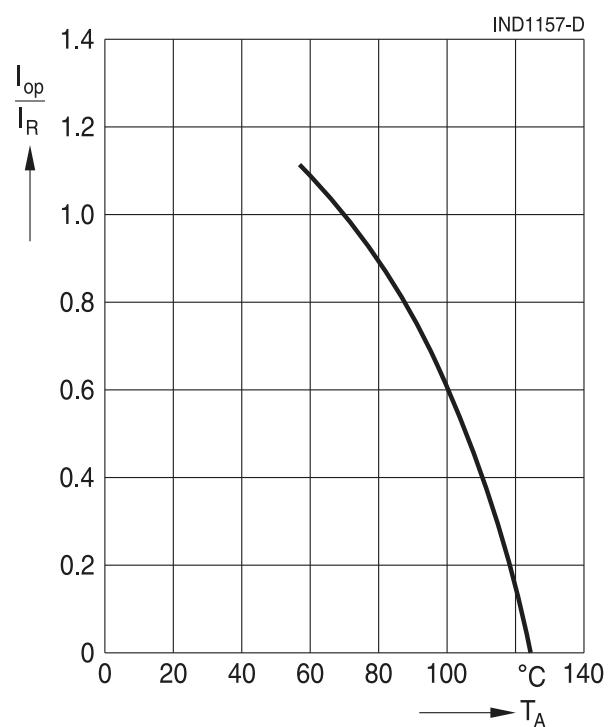
**Characteristics and ordering codes**

$I_R$	$L_R$	$L_{stray,typ}$	$R_{typ}$	Wire Ø d ±0.1	Ordering code
A	mH	µH	mΩ	mm	
10	1.7	14	9.8	1.25	B82746S4103A020
10	2.0	20	9.6	1.4	B82746S4103A021

**Impedance  $|Z|$  versus frequency  $f$**   
measured with windings in parallel at +20 °C,  
typical value



**Current derating  $I_{op}/I_R$**   
**versus ambient temperature  $T_A$**   
rated temperature  $T_R = +70$  °C



## Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.  
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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